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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2566
Number of Logic Elements/Cells	25660
Total RAM Bits	1944576
Number of I/O	473
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA
Supplier Device Package	672-FBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s25f672c8



Chapter Revision Dates

The chapters in this book, *Stratix Device Handbook, Volume 1*, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

- Chapter 1. Introduction
Revised: *July 2005*
Part number: *S51001-3.2*
- Chapter 2. Stratix Architecture
Revised: *July 2005*
Part number: *S51002-3.2*
- Chapter 3. Configuration & Testing
Revised: *July 2005*
Part number: *S51003-1.3*
- Chapter 4. DC & Switching Characteristics
Revised: *January 2006*
Part number: *S51004-3.4*
- Chapter 5. Reference & Ordering Information
Revised: *September 2004*
Part number: *S51005-2.1*



About This Handbook

This handbook provides comprehensive information about the Altera® Stratix family of devices.

How to Find Information

You can find more information in the following ways:

- The Adobe Acrobat Find feature, which searches the text of a PDF document. Click the binoculars toolbar icon to open the Find dialog box.
- Acrobat bookmarks, which serve as an additional table of contents in PDF documents.
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Section I. Stratix Device Family Data Sheet

This section provides the data sheet specifications for Stratix® devices. They contain feature definitions of the internal architecture, configuration and JTAG boundary-scan testing information, DC operating conditions, AC timing parameters, a reference to power consumption, and ordering information for Stratix devices.

This section contains the following chapters:

- Chapter 1, Introduction
- Chapter 2, Stratix Architecture
- Chapter 3, Configuration & Testing
- Chapter 4, DC & Switching Characteristics
- Chapter 5, Reference & Ordering Information

Revision History

The table below shows the revision history for Chapters 1 through 5.

Chapter	Date/Version	Changes Made
1	July 2005, v3.2	● Minor content changes.
	September 2004, v3.1	● Updated Table 1–6 on page 1–5.
	April 2004, v3.0	● Main section page numbers changed on first page. ● Changed PCI-X to PCI-X 1.0 in “Features” on page 1–2. ● Global change from SignalTap to SignalTap II. ● The DSP blocks in “Features” on page 1–2 provide dedicated implementation of multipliers that are now “faster than 300 MHz.”
	January 2004, v2.2	● Updated -5 speed grade device information in Table 1-6.
	October 2003, v2.1	● Add -8 speed grade device information.
	July 2003, v2.0	● Format changes throughout chapter.

Table 1–1. Stratix Device Features — EP1S10, EP1S20, EP1S25, EP1S30

Feature	EP1S10	EP1S20	EP1S25	EP1S30
LEs	10,570	18,460	25,660	32,470
M512 RAM blocks (32×18 bits)	94	194	224	295
M4K RAM blocks (128×36 bits)	60	82	138	171
M-RAM blocks ($4K \times 144$ bits)	1	2	2	4
Total RAM bits	920,448	1,669,248	1,944,576	3,317,184
DSP blocks	6	10	10	12
Embedded multipliers (1)	48	80	80	96
PLLs	6	6	6	10
Maximum user I/O pins	426	586	706	726

Table 1–2. Stratix Device Features — EP1S40, EP1S60, EP1S80

Feature	EP1S40	EP1S60	EP1S80
LEs	41,250	57,120	79,040
M512 RAM blocks (32×18 bits)	384	574	767
M4K RAM blocks (128×36 bits)	183	292	364
M-RAM blocks ($4K \times 144$ bits)	4	6	9
Total RAM bits	3,423,744	5,215,104	7,427,520
DSP blocks	14	18	22
Embedded multipliers (1)	112	144	176
PLLs	12	12	12
Maximum user I/O pins	822	1,022	1,238

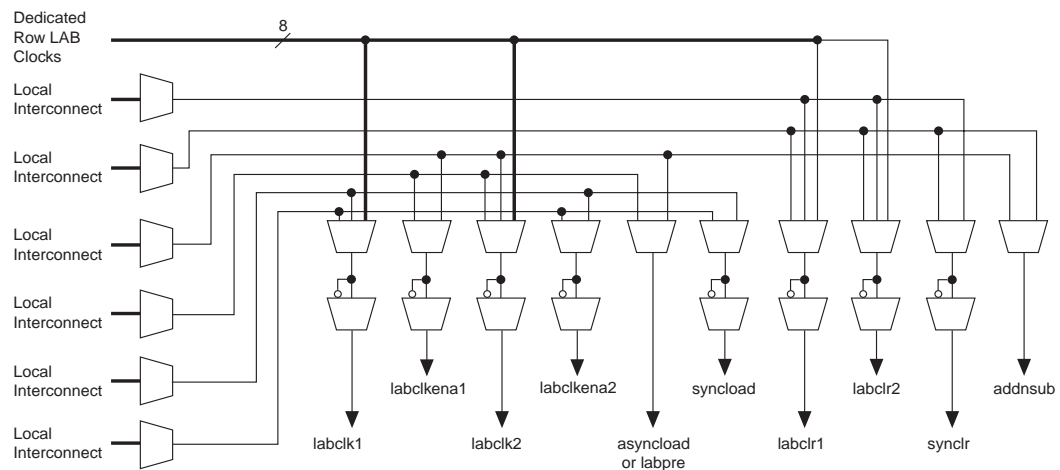
Note to Tables 1–1 and 1–2:

- (1) This parameter lists the total number of 9×9 -bit multipliers for each device. For the total number of 18×18 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 2. For the total number of 36×36 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 8.

With the LAB-wide `addnsub` control signal, a single LE can implement a one-bit adder and subtractor. This saves LE resources and improves performance for logic functions such as DSP correlators and signed multipliers that alternate between addition and subtraction depending on data.

The LAB row clocks [7..0] and LAB local interconnect generate the LAB-wide control signals. The MultiTrack™ interconnect's inherent low skew allows clock and control signal distribution in addition to data. [Figure 2–4](#) shows the LAB control signal generation circuit.

Figure 2–4. LAB-Wide Control Signals



Logic Elements

The smallest unit of logic in the Stratix architecture, the LE, is compact and provides advanced features with efficient logic utilization. Each LE contains a four-input LUT, which is a function generator that can implement any function of four variables. In addition, each LE contains a programmable register and carry chain with carry select capability. A single LE also supports dynamic single bit addition or subtraction mode selectable by an LAB-wide control signal. Each LE drives all types of interconnects: local, row, column, LUT chain, register chain, and direct link interconnects. See [Figure 2–5](#).

functions. Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT. This provides another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

LUT Chain & Register Chain

In addition to the three general routing outputs, the LEs within an LAB have LUT chain and register chain outputs. LUT chain connections allow LUTs within the same LAB to cascade together for wide input functions. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows an LAB to use LUTs for a single combinatorial function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. See [“MultiTrack Interconnect” on page 2–14](#) for more information on LUT chain and register chain connections.

addnsub Signal

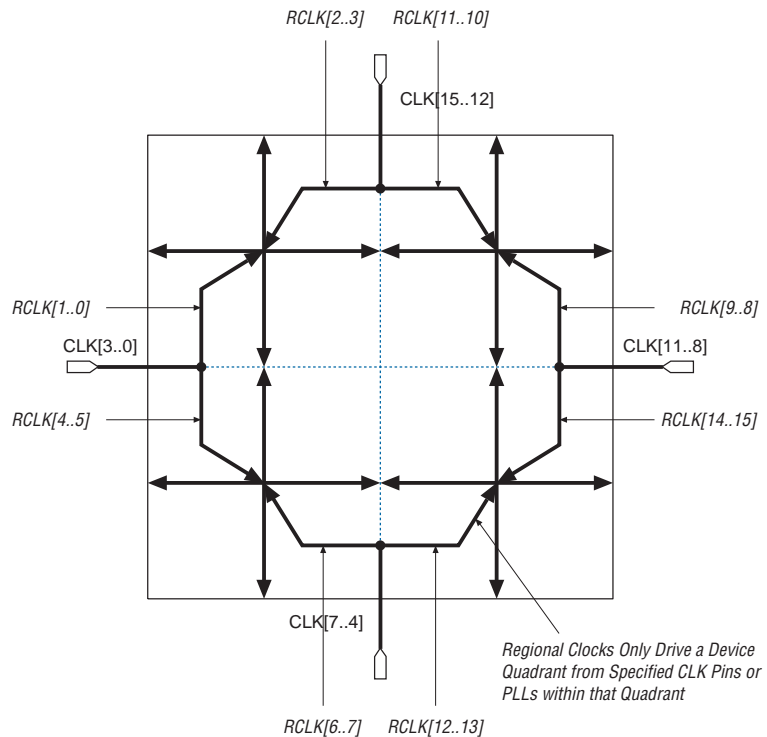
The LE's dynamic adder/subtractor feature saves logic resources by using one set of LEs to implement both an adder and a subtractor. This feature is controlled by the LAB-wide control signal `addnsub`. The `addnsub` signal sets the LAB to perform either $A + B$ or $A - B$. The LUT computes addition, and subtraction is computed by adding the two's complement of the intended subtractor. The LAB-wide signal converts to two's complement by inverting the B bits within the LAB and setting carry-in = 1 to add one to the least significant bit (LSB). The LSB of an adder/subtractor must be placed in the first LE of the LAB, where the LAB-wide `addnsub` signal automatically sets the carry-in to 1. The Quartus II Compiler automatically places and uses the adder/subtractor feature when using adder/subtractor parameterized functions.

LE Operating Modes

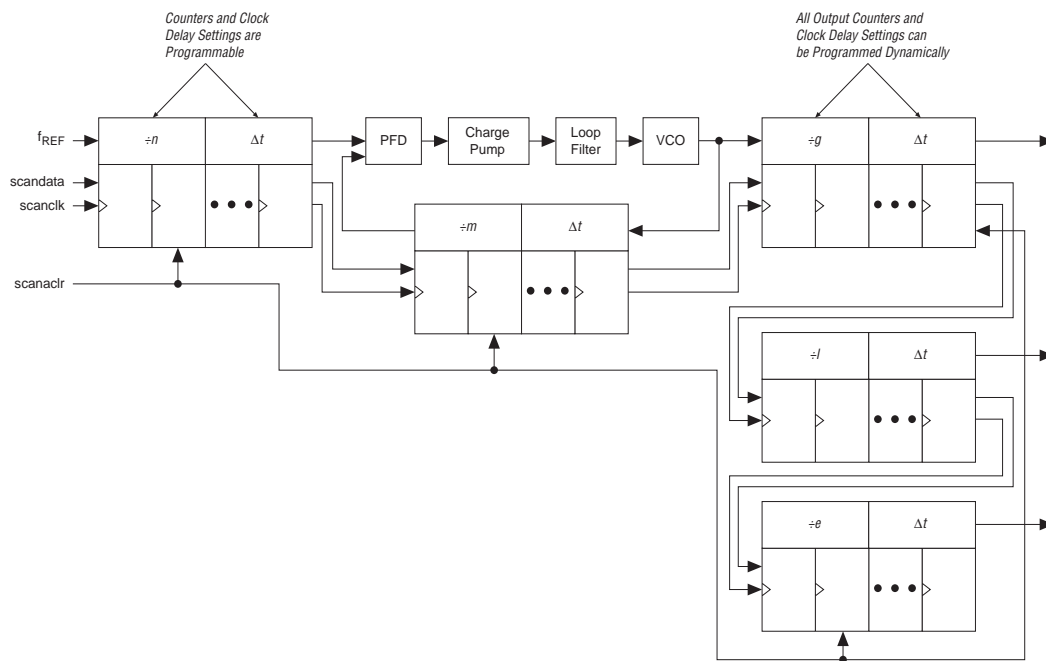
The Stratix LE can operate in one of the following modes:

- Normal mode
- Dynamic arithmetic mode

Each mode uses LE resources differently. In each mode, eight available inputs to the LE—the four data inputs from the LAB local interconnect; `carry-in0` and `carry-in1` from the previous LE; the LAB carry-in from the previous carry-chain LAB; and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear,

Figure 2–43. Regional Clocks**Fast Regional Clock Network**

In EP1S25, EP1S20, and EP1S10 devices, there are two fast regional clock networks, FCLK [1 . . 0], within each quadrant, fed by input pins that can connect to fast regional clock networks (see [Figure 2–44](#)). In EP1S30 and larger devices, there are two fast regional clock networks within each half-quadrant (see [Figure 2–45](#)). Dual-purpose FCLK pins drive the fast clock networks. All devices have eight FCLK pins to drive fast regional clock networks. Any I/O pin can drive a clock or control signal onto any fast regional clock network with the addition of a delay. This signal is driven via the I/O interconnect. The fast regional clock networks can also be driven from internal logic elements.

Figure 2–54. Dynamically Programmable Counters & Delays in Stratix Device Enhanced PLLs

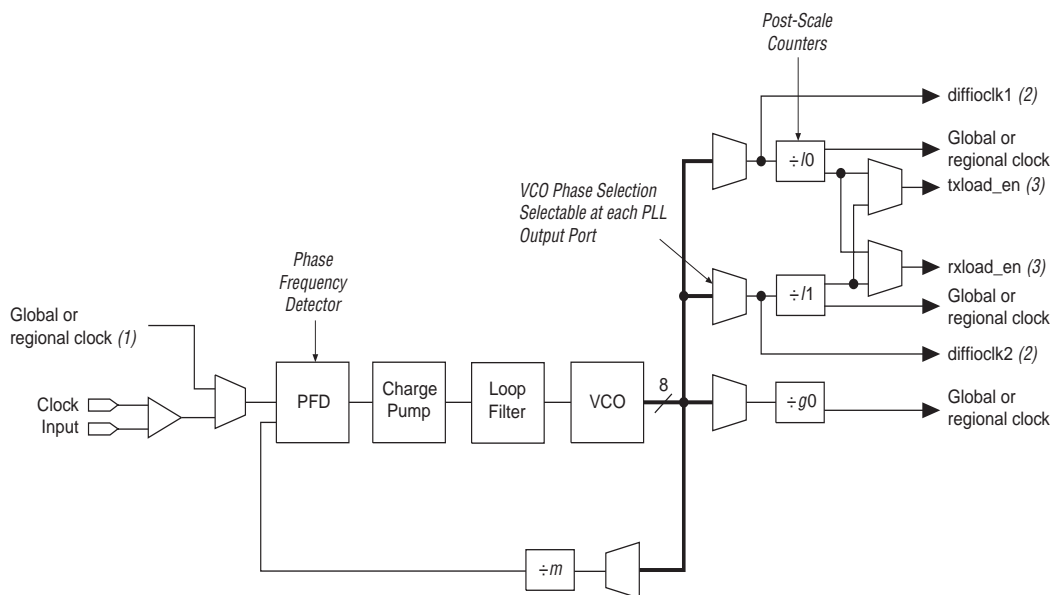
PLL reconfiguration data is shifted into serial registers from the logic array or external devices. The PLL input shift data uses a reference input shift clock. Once the last bit of the serial chain is clocked in, the register chain is synchronously loaded into the PLL configuration bits. The shift circuitry also provides an asynchronous clear for the serial registers.



For more information on PLL reconfiguration, see *AN 282: Implementing PLL Reconfiguration in Stratix & Stratix GX Devices*.

Programmable Bandwidth

You have advanced control of the PLL bandwidth using the programmable control of the PLL loop characteristics, including loop filter and charge pump. The PLL's bandwidth is a measure of its ability to track the input clock and jitter. A high-bandwidth PLL can quickly lock onto a reference clock and react to any changes in the clock. It also will allow a wide band of input jitter spectrum to pass to the output. A low-bandwidth PLL will take longer to lock, but it will attenuate all high-frequency jitter components. The Quartus II software can adjust PLL characteristics to achieve the desired bandwidth. The programmable

Figure 2–58. Stratix Device Fast PLL**Notes to Figure 2–58:**

- (1) The global or regional clock input can be driven by an output from another PLL or any dedicated CLK or FCLK pin. It cannot be driven by internally-generated global signals.
- (2) In high-speed differential I/O support mode, this high-speed PLL clock feeds the SERDES. Stratix devices only support one rate of data transfer per fast PLL in high-speed differential I/O support mode.
- (3) This signal is a high-speed differential I/O support SERDES control signal.

Clock Multiplication & Division

Stratix device fast PLLs provide clock synthesis for PLL output ports using m /(post scaler) scaling factors. The input clock is multiplied by the m feedback factor. Each output port has a unique post scale counter to divide down the high-frequency VCO. There is one multiply divider, m , per fast PLL with a range of 1 to 32. There are two post scale L dividers for regional and/or LVDS interface clocks, and $g0$ counter for global clock output port; all range from 1 to 32.

In the case of a high-speed differential interface, set the output counter to 1 to allow the high-speed VCO frequency to drive the SERDES. When used for clocking the SERDES, the m counter can range from 1 to 30. The VCO frequency is equal to $f_{IN} \times m$, where VCO frequency must be between 300 and 1000 MHz.

Table 2–22. Fast PLL Port I/O Standards (Part 2 of 2)

I/O Standard	Input	
	INCLK	PLENABLE
SSTL-2 Class II	✓	
SSTL-3 Class I	✓	
SSTL-3 Class II	✓	
AGP (1× and 2×)		
CTT	✓	

Table 2–23 shows the performance on each of the fast PLL clock inputs when using LVDS, LVPECL, 3.3-V PCML, or HyperTransport technology.

Table 2–23. LVDS Performance on Fast PLL Input

Fast PLL Clock Input	Maximum Input Frequency (MHz)
CLK0, CLK2, CLK9, CLK11, FPLL7CLK, FPLL8CLK, FPLL9CLK, FPLL10CLK	717 ⁽¹⁾
CLK1, CLK3, CLK8, CLK10	645

Note to Table 2–23:

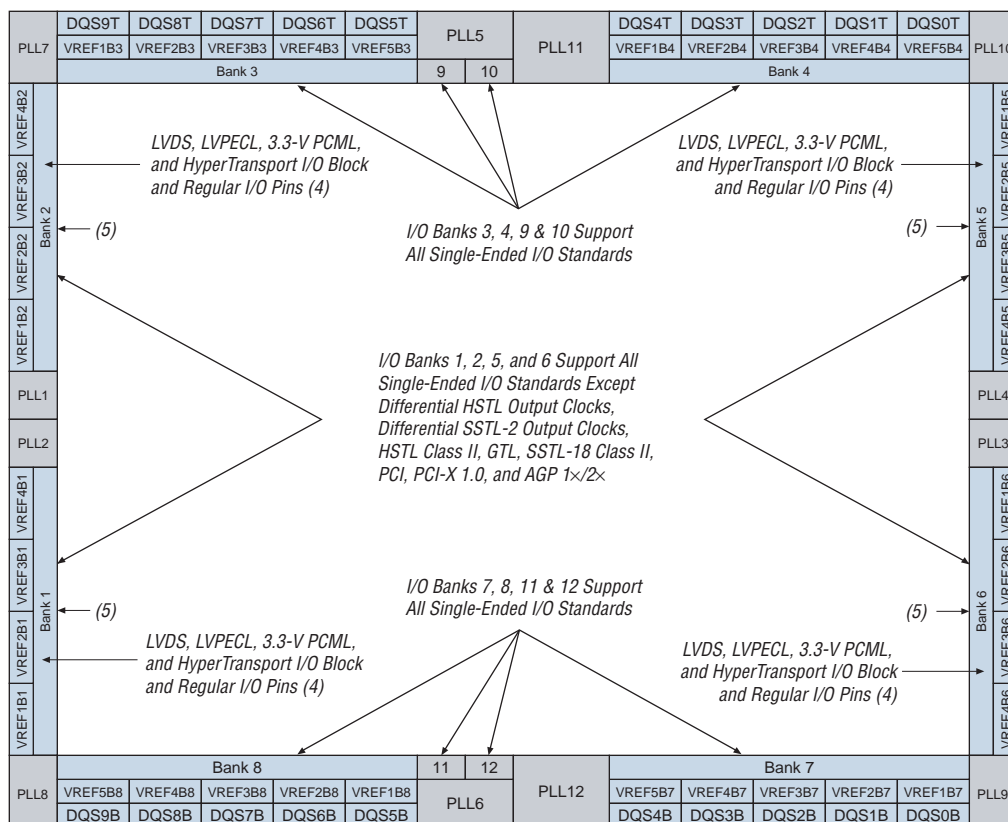
- (1) See the chapter *DC & Switching Characteristics* of the *Stratix Device Handbook, Volume 1* for more information.

External Clock Outputs

Each fast PLL supports differential or single-ended outputs for source-synchronous transmitters or for general-purpose external clocks. There are no dedicated external clock output pins. Any I/O pin can be driven by the fast PLL global or regional outputs as an external output pin. The I/O standards supported by any particular bank determines what standards are possible for an external clock output driven by the fast PLL in that bank.

Phase Shifting

Stratix device fast PLLs have advanced clock shift capability that enables programmable phase shifts. You can enter a phase shift (in degrees or time units) for each PLL clock output port or for all outputs together in one shift. You can perform phase shifting in time units with a resolution range of 125 to 416.66 ps. This resolution is a function of the VCO period, with the finest step being equal to an eighth (×0.125) of the VCO period.

Figure 2–70. Stratix I/O Banks *Notes (1), (2), (3)***Notes to Figure 2–70:**

- (1) Figure 2–70 is a top view of the silicon die. This will correspond to a top-down view for non-flip-chip packages, but will be a reverse view for flip-chip packages.
- (2) Figure 2–70 is a graphic representation only. See the device pin-outs on the web (www.altera.com) and the Quartus II software for exact locations.
- (3) Banks 9 through 12 are enhanced PLL external clock output banks.
- (4) If the high-speed differential I/O pins are not used for high-speed differential signaling, they can support all of the I/O standards except HSTL Class I and II, GTL, SSTL-18 Class II, PCI, PCI-X 1.0, and AGP 1x/2x.
- (5) For guidelines for placing single-ended I/O pads next to differential I/O pads, see the *Selectable I/O Standards in Stratix and Stratix GX Devices* chapter in the *Stratix Device Handbook, Volume 2*.

Figure 3–1 shows the timing requirements for the JTAG signals.

Figure 3–1. Stratix JTAG Waveforms

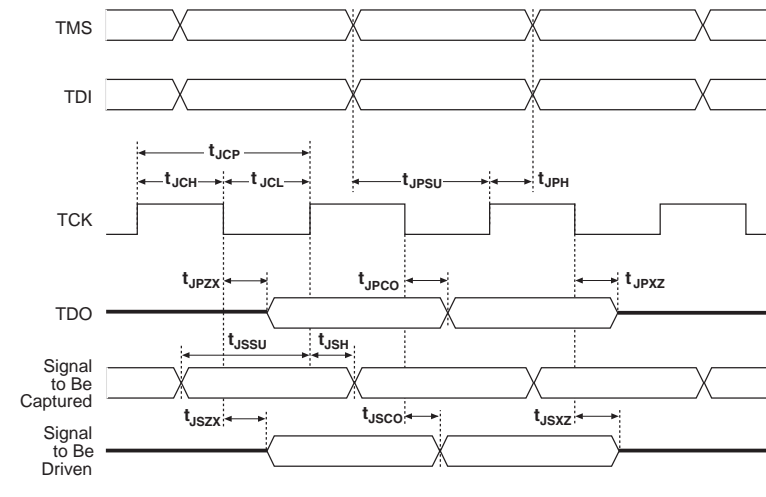


Table 3–4 shows the JTAG timing parameters and values for Stratix devices.

Table 3–4. Stratix JTAG Timing Parameters & Values				
Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	100		ns
t_{JCH}	TCK clock high time	50		ns
t_{JCL}	TCK clock low time	50		ns
t_{JPSU}	JTAG port setup time	20		ns
t_{JPH}	JTAG port hold time	45		ns
t_{JPCO}	JTAG port clock to output		25	ns
t_{JPZX}	JTAG port high impedance to valid output		25	ns
t_{JPXZ}	JTAG port valid output to high impedance		25	ns
t_{JSSU}	Capture register setup time	20		ns
t_{JSH}	Capture register hold time	45		ns
t_{JSCO}	Update register clock to output		35	ns
t_{JSZX}	Update register high impedance to valid output		35	ns
t_{JSXZ}	Update register valid output to high impedance		35	ns

Table 4–7. 1.8-V I/O Specifications

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V _{CCIO}	Output supply voltage		1.65	1.95	V
V _{IH}	High-level input voltage		0.65 × V _{CCIO}	2.25	V
V _{IL}	Low-level input voltage		–0.3	0.35 × V _{CCIO}	V
V _{OH}	High-level output voltage	I _{OH} = –2 to –8 mA (10)	V _{CCIO} – 0.45		V
V _{OL}	Low-level output voltage	I _{OL} = 2 to 8 mA (10)		0.45	V

Table 4–8. 1.5-V I/O Specifications

Symbol	Parameter	Conditions	Minimum	Maximum	Unit
V _{CCIO}	Output supply voltage		1.4	1.6	V
V _{IH}	High-level input voltage		0.65 × V _{CCIO}	V _{CCIO} + 0.3	V
V _{IL}	Low-level input voltage		–0.3	0.35 × V _{CCIO}	V
V _{OH}	High-level output voltage	I _{OH} = –2 mA (10)	0.75 × V _{CCIO}		V
V _{OL}	Low-level output voltage	I _{OL} = 2 mA (10)		0.25 × V _{CCIO}	V

Notes to Tables 4–1 through 4–8:

- (1) See the *Operating Requirements for Altera Devices Data Sheet*.
- (2) Conditions beyond those listed in Table 4–1 may cause permanent damage to a device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse affects on the device.
- (3) Minimum DC input is –0.5 V. During transitions, the inputs may undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns, or overshoot to the voltage shown in Table 4–9, based on input duty cycle for input currents less than 100 mA. The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to 100% duty cycle.
- (4) Maximum V_{CC} rise time is 100 ms, and V_{CC} must rise monotonically.
- (5) V_{CCIO} maximum and minimum conditions for LVPECL, LVDS, and 3.3-V PCML are shown in parentheses.
- (6) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before V_{CCINT} and V_{CCIO} are powered.
- (7) Typical values are for T_A = 25°C, V_{CCINT} = 1.5 V, and V_{CCIO} = 1.5 V, 1.8 V, 2.5 V, and 3.3 V.
- (8) This value is specified for normal device operation. The value may vary during power-up. This applies for all V_{CCIO} settings (3.3, 2.5, 1.8, and 1.5 V).
- (9) Pin pull-up resistance values will lower if an external source drives the pin higher than V_{CCIO}.
- (10) Drive strength is programmable according to the values shown in the *Stratix Architecture* chapter of the *Stratix Device Handbook, Volume 1*.

Table 4–9. Overshoot Input Voltage with Respect to Duty Cycle (Part 1 of 2)

V _{in} (V)	Maximum Duty Cycle (%)
4.0	100
4.1	90
4.2	50

Table 4–28. 1.8-V HSTL Class I Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	Output supply voltage		1.65	1.80	1.95	V
V_{REF}	Input reference voltage		0.70	0.90	0.95	V
V_{TT}	Termination voltage			$V_{CCIO} \times 0.5$		V
$V_{IH} (DC)$	DC high-level input voltage		$V_{REF} + 0.1$			V
$V_{IL} (DC)$	DC low-level input voltage		–0.5		$V_{REF} - 0.1$	V
$V_{IH} (AC)$	AC high-level input voltage		$V_{REF} + 0.2$			V
$V_{IL} (AC)$	AC low-level input voltage				$V_{REF} - 0.2$	V
V_{OH}	High-level output voltage	$I_{OH} = -8 \text{ mA}$ (3)	$V_{CCIO} - 0.4$			V
V_{OL}	Low-level output voltage	$I_{OL} = 8 \text{ mA}$ (3)			0.4	V

Table 4–29. 1.8-V HSTL Class II Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	Output supply voltage		1.65	1.80	1.95	V
V_{REF}	Input reference voltage		0.70	0.90	0.95	V
V_{TT}	Termination voltage			$V_{CCIO} \times 0.5$		V
$V_{IH} (DC)$	DC high-level input voltage		$V_{REF} + 0.1$			V
$V_{IL} (DC)$	DC low-level input voltage		–0.5		$V_{REF} - 0.1$	V
$V_{IH} (AC)$	AC high-level input voltage		$V_{REF} + 0.2$			V
$V_{IL} (AC)$	AC low-level input voltage				$V_{REF} - 0.2$	V
V_{OH}	High-level output voltage	$I_{OH} = -16 \text{ mA}$ (3)	$V_{CCIO} - 0.4$			V
V_{OL}	Low-level output voltage	$I_{OL} = 16 \text{ mA}$ (3)			0.4	V

Table 4–30. 1.5-V Differential HSTL Class I & Class II Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{CCIO}	I/O supply voltage		1.4	1.5	1.6	V
$V_{DIF} (DC)$	DC input differential voltage		0.2			V
$V_{CM} (DC)$	DC common mode input voltage		0.68		0.9	V
$V_{DIF} (AC)$	AC differential input voltage		0.4			V

Table 4–63. EP1S20 External I/O Timing on Column Pins Using Global Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	1.351		1.479		1.699		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.732	5.380	2.732	5.728	2.732	6.240	NA	NA	ns
t_{XZ}	2.672	5.254	2.672	5.596	2.672	6.116	NA	NA	ns
t_{ZX}	2.672	5.254	2.672	5.596	2.672	6.116	NA	NA	ns
t_{INSUPLL}	0.923		0.971		1.098		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.210	2.544	1.210	2.648	1.210	2.715	NA	NA	ns
t_{XZPLL}	1.150	2.418	1.150	2.516	1.150	2.591	NA	NA	ns
t_{ZXPLL}	1.150	2.418	1.150	2.516	1.150	2.591	NA	NA	ns

Table 4–64. EP1S20 External I/O Timing on Row Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.032		2.207		2.535		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.492	5.018	2.492	5.355	2.492	5.793	NA	NA	ns
t_{XZ}	2.519	5.072	2.519	5.411	2.519	5.861	NA	NA	ns
t_{ZX}	2.519	5.072	2.519	5.411	2.519	5.861	NA	NA	ns

Tables 4–79 through 4–84 show the external timing parameters on column and row pins for EP1S40 devices.

Table 4–79. EP1S40 External I/O Timing on Column Pins Using Fast Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.696		2.907		3.290		2.899		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.506	5.015	2.506	5.348	2.506	5.809	2.698	7.286	ns
t_{xZ}	2.446	4.889	2.446	5.216	2.446	5.685	2.638	7.171	ns
t_{ZX}	2.446	4.889	2.446	5.216	2.446	5.685	2.638	7.171	ns

Table 4–80. EP1S40 External I/O Timing on Column Pins Using Regional Clock Networks

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.413		2.581		2.914		2.938		ns
t_{INH}	0.000		0.000		0.000		0.000		ns
t_{OUTCO}	2.668	5.254	2.668	5.628	2.668	6.132	2.869	7.307	ns
t_{xZ}	2.608	5.128	2.608	5.496	2.608	6.008	2.809	7.192	ns
t_{ZX}	2.608	5.128	2.608	5.496	2.608	6.008	2.809	7.192	ns
t_{INSUPLL}	1.385		1.376		1.609		1.837		ns
t_{INHPLL}	0.000		0.000		0.000		0.000		ns
t_{OUTCOPLL}	1.117	2.382	1.117	2.552	1.117	2.504	1.117	2.542	ns
t_{xZPLL}	1.057	2.256	1,057	2.420	1.057	2.380	1.057	2.427	ns
t_{ZXPLL}	1.057	2.256	1,057	2.420	1.057	2.380	1.057	2.427	ns

Tables 4–85 through 4–90 show the external timing parameters on column and row pins for EP1S60 devices.

Table 4–85. EP1S60 External I/O Timing on Column Pins Using Fast Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	3.029		3.277		3.733		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.446	4.871	2.446	5.215	2.446	5.685	NA	NA	ns
t_{xZ}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns
t_{ZX}	2.386	4.745	2.386	5.083	2.386	5.561	NA	NA	ns

Table 4–86. EP1S60 External I/O Timing on Column Pins Using Regional Clock Networks *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.491		2.691		3.060		NA		ns
t_{INH}	0.000		0.000		0.000		NA		ns
t_{OUTCO}	2.767	5.409	2.767	5.801	2.767	6.358	NA	NA	ns
t_{xZ}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{ZX}	2.707	5.283	2.707	5.669	2.707	6.234	NA	NA	ns
t_{INSUPLL}	1.233		1.270		1.438		NA		ns
t_{INHPLL}	0.000		0.000		0.000		NA		ns
t_{OUTCOPLL}	1.078	2.278	1.078	2.395	1.078	2.428	NA	NA	ns
t_{xZPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns
t_{ZXPLL}	1.018	2.152	1.018	2.263	1.018	2.304	NA	NA	ns

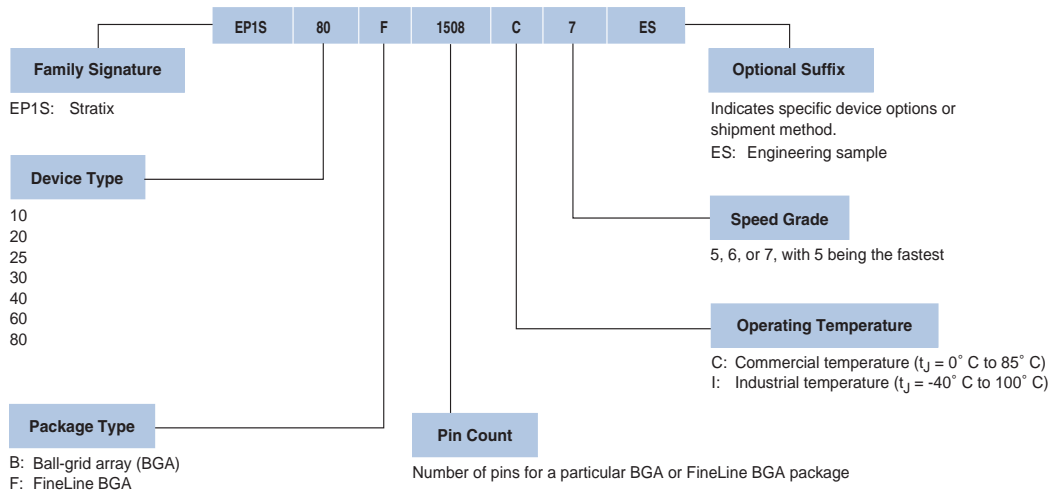
Table 4–128. Enhanced PLL Specifications for -6 Speed Grades (Part 2 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
t _{SCANCLK}	scanclk frequency (5)			22	MHz
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays) (7) (11)	(9)		100	μs
t _{LOCK}	Time required to lock from end of device configuration (11)	10		400	μs
f _{VCO}	PLL internal VCO operating range	300		800 (8)	MHz
t _{LSKEW}	Clock skew between two external clock outputs driven by the same counter		±50		ps
t _{SKEW}	Clock skew between two external clock outputs driven by the different counters with the same settings		±75		ps
f _{SS}	Spread spectrum modulation frequency	30		150	kHz
% spread	Percentage spread for spread spectrum frequency (10)	0.4	0.5	0.6	%
t _{ARESET}	Minimum pulse width on areset signal	10			ns

Table 4–129. Enhanced PLL Specifications for -7 Speed Grade (Part 1 of 2)

Symbol	Parameter	Min	Typ	Max	Unit
f _{IN}	Input clock frequency	3 (1), (2)		565	MHz
f _{INPFD}	Input frequency to PFD	3		420	MHz
f _{INDUTY}	Input clock duty cycle	40		60	%
f _{EINDUTY}	External feedback clock input duty cycle	40		60	%
t _{INJITTER}	Input clock period jitter			±200 (3)	ps
t _{EINJITTER}	External feedback clock period jitter			±200 (3)	ps
t _{FCOMP}	External feedback clock compensation time (4)			6	ns
f _{OUT}	Output frequency for internal global or regional clock	0.3		420	MHz
f _{OUT_EXT}	Output frequency for external clock (3)	0.3		434	MHz

Figure 5–1. Stratix Device Packaging Ordering Information



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